

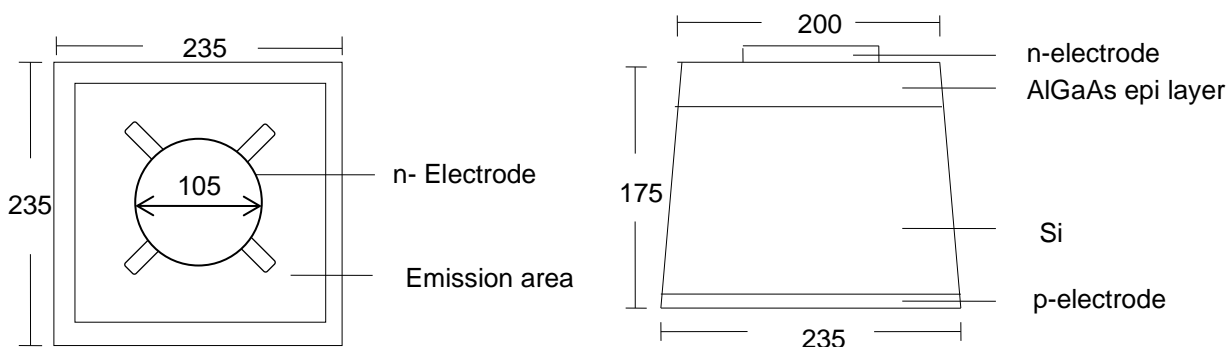
### ■ Features :

- Suitable for New Creative Products

### ■ Typical Applications :

- Home entertainment
- Light source for CMOS & CCD camera
- Security camera, CCTV

### ■ Outline Dimensions : (Unit: $\mu\text{m}$ )



### ■ Physical Structure :

Chip dimension	Chip size	235 x 235 $\mu\text{m}$ $\pm$ 20 $\mu\text{m}$
	Thickness	175 $\pm$ 25 $\mu\text{m}$
	Emission area	200 $\mu\text{m}$
	Bonding pad	105 $\mu\text{m}$
Electrode	Top: N (cathode)	Gold
	Backside: P (anode)	Gold
Surface condition	Frosted	

\*C2

### ■ Electro-Optical Characteristics : ( $T_a = 25^\circ\text{C}$ )

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward voltage	$V_{FH}$	$I_F = 50\text{mA}$	1.50	-	1.80	V
Reverse current	$I_R$	$V_R = 10\text{V}$	-	-	1	$\mu\text{A}$
Radiant Power	$P_o$	$I_F = 50\text{mA}$	6.0	-	10	mW
Wavelength	$\lambda_P$	$I_F = 50\text{mA}$	870	-	900	Nm
Spectral width at half height	$\Delta\lambda$	$I_F = 50\text{mA}$	-	40	-	nm

■ Typical Electro-Optical Characteristics Curve:

Fig 1. Forward Current vs. Forward Voltage

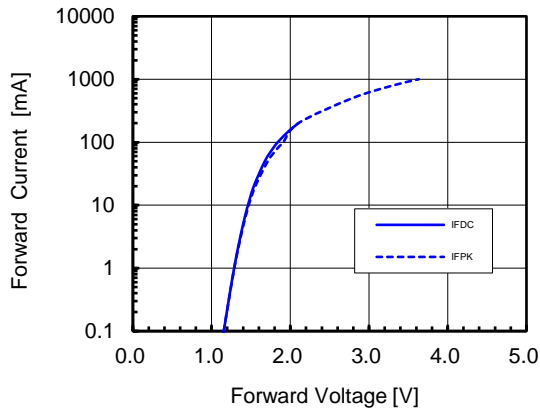


Fig 2. Relative Radiant Power vs. Wavelength

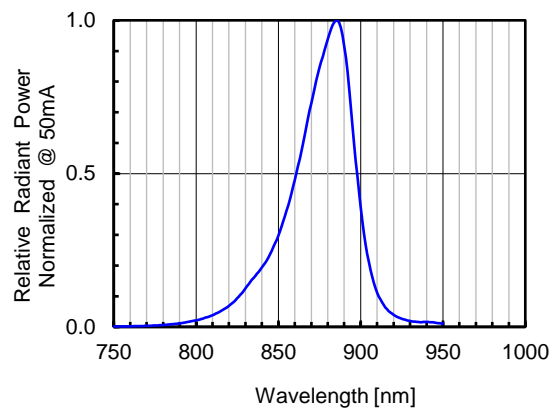


Fig 3. Relative Radiant Power vs. Forward DC Current

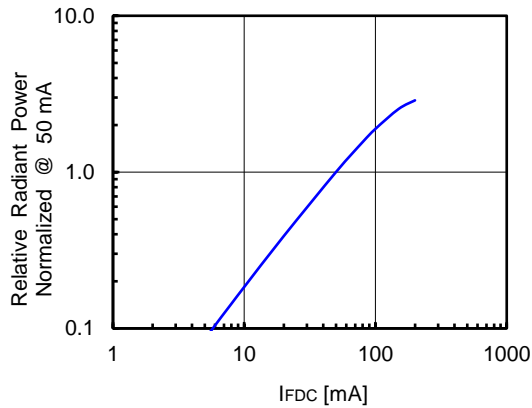


Fig 4. Relative Radiant Power vs. Forward Peak Current

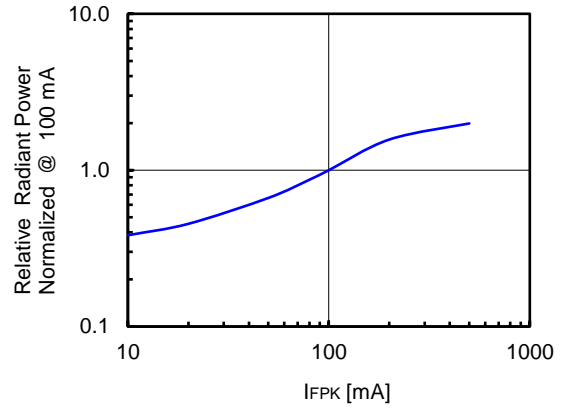


Fig 5. Forward DC Voltage vs. Temperature

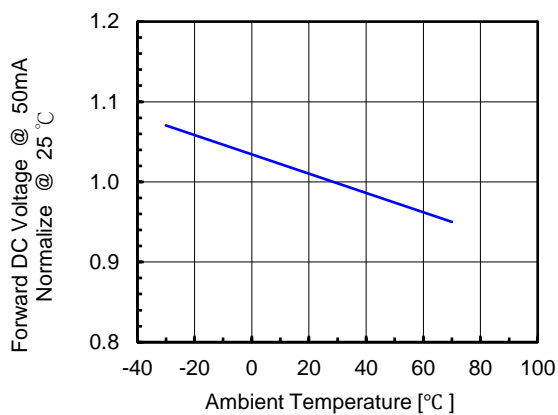


Fig 6. Relative Radiant Power vs. Temperature

